



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

AAAF5060BESEEVG

BLUE / HYPER ORANGE / GREEN

Features

- CHIPS CAN BE CONTROLLED SEPARATELY.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- PACKAGE: 500PCS / REEL.

Description

The Blue source color devices are made with InGaN on SiC Light Emitting Diode.

The Hyper Orange source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

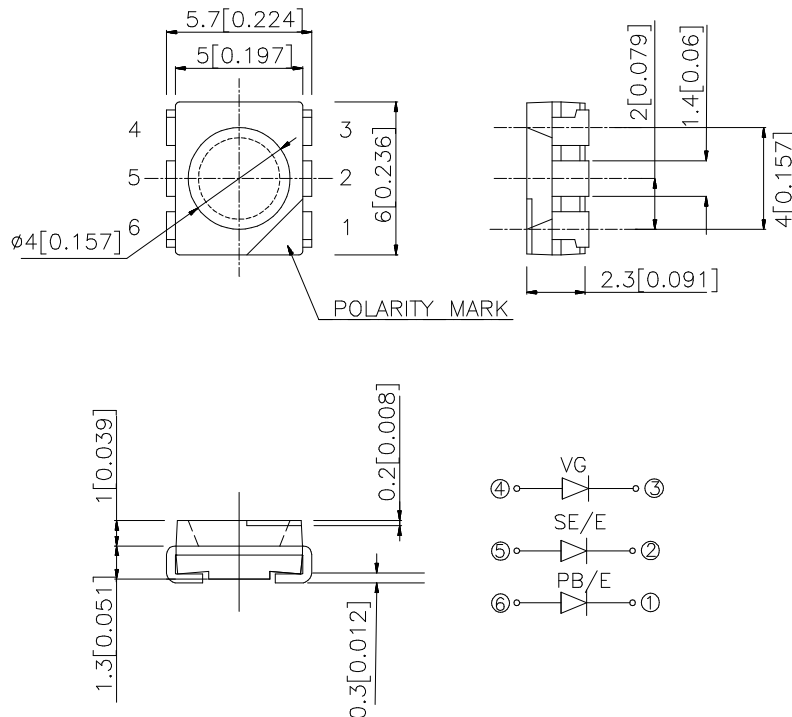
The Green source color devices are made with InGaN on SiC Light Emitting Diode.

Static electricity and surge damage the LEDs.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25 (0.01)$ unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 30mA *50mA		Viewing Angle
			Min.	Typ.	
AAAF5060BESEEVG	BLUE (InGaN)	WATER CLEAR	110	250	100°
	HYPER ORANGE(InGaAlP)		*650	*1000	
	GREEN (InGaN)		180	350	

Notes:

1. $\theta_{1/2}$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. * Luminous intensity with asterisk is measured at 50mA.

Electrical / Optical Characteristics at T_A=25°C

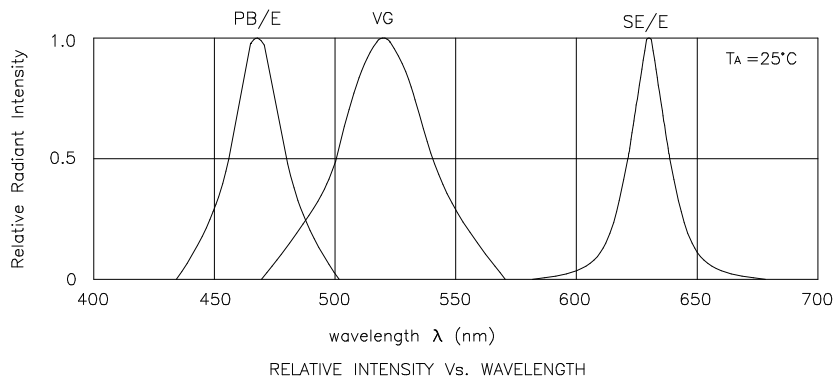
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Blue Hyper Orange Green	465 630 520		nm	I _F =20mA
λ_D	Dominate Wavelength	Blue Hyper Orange Green	470 621 525		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Blue Hyper Orange Green	25 20 38		nm	I _F =20mA
C	Capacitance	Blue Hyper Orange Green	110 25 45		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Blue Hyper Orange Green	3.7 2.0 4.0	4.3 2.5 4.5	V	I _F =20mA
I _R	Reverse Current	All		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Blue	Hyper Orange	Green	Units
Total Power dissipation t [1]	350			mW
DC Forward Current	30	50	30	mA
Peak Forward Current [2]	160	195	150	mA
Reverse Voltage	5	5	5	V
Operating/Storage Temperature	-40°C To +85°C			

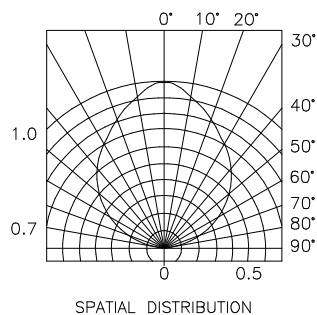
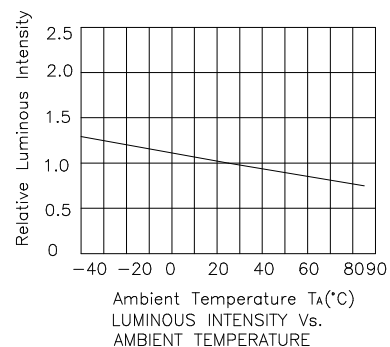
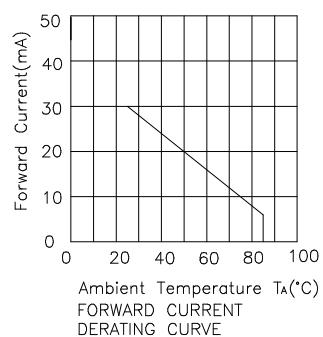
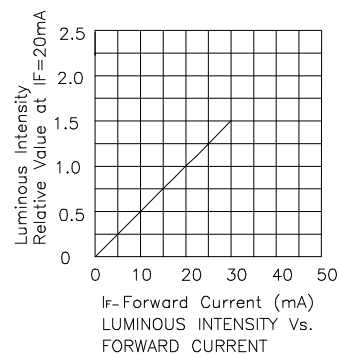
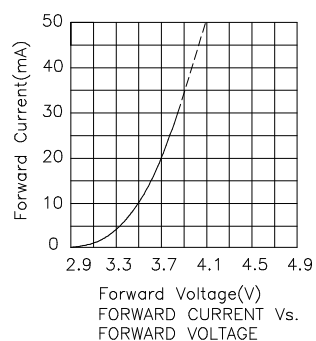
Notes:

1. Within 350mW at all chips are lightened.
2. 1/10 Duty Cycle, 0.1ms Pulse Width.

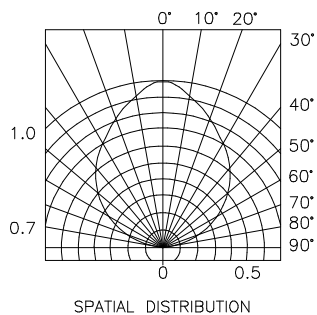
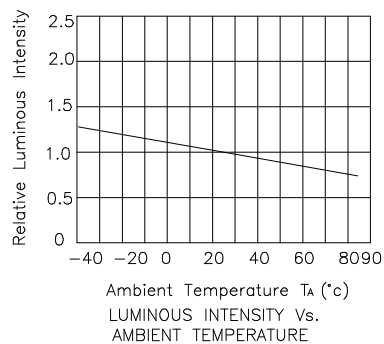
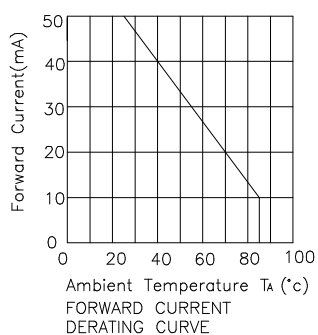
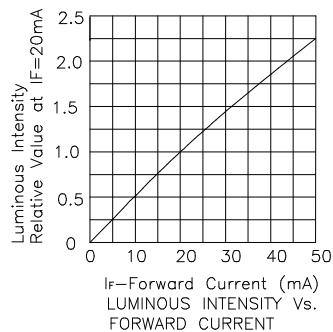
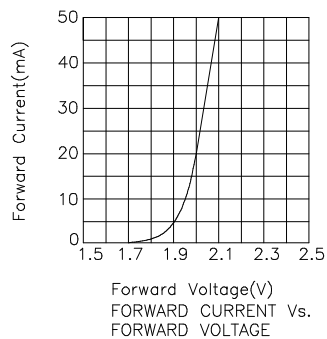


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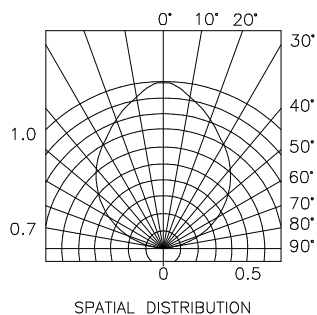
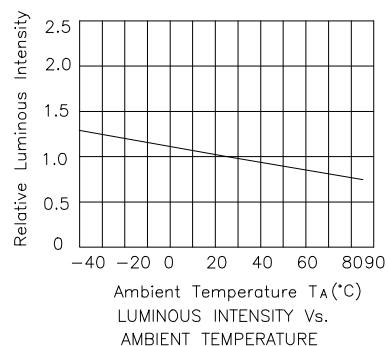
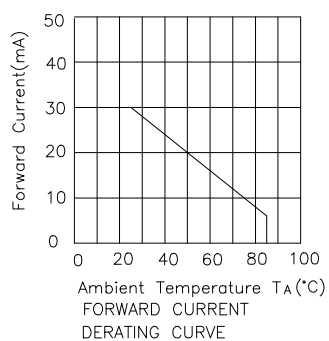
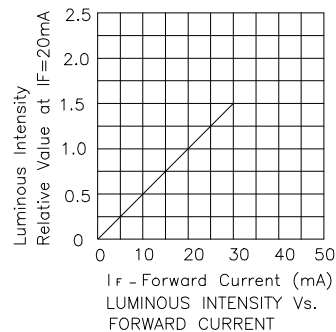
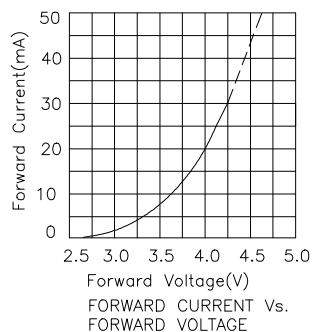
Blue



Hyper Orange



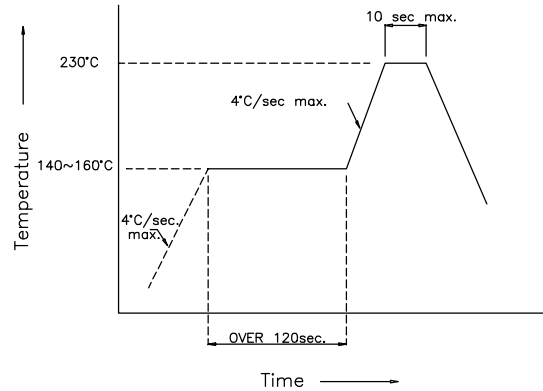
Green



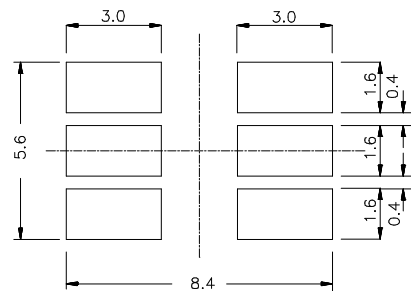
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SMT Reflow Soldering Instruction

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

